

REMARKS/ARGUMENTS

Rejection of claims 1, 5, 13 and 16-21 under 35 U.S.C 103(a) as being unpatentable over Applicant's admitted prior art (APA), figures 1-2, in view
5 **of Sato, US 2006/0097380.**

Claims 1 and 13 of the present invention recite a liquid crystal display module having a glass substrate and at least a driver chip (such as a gate driver chip or a source driver chip) mounted on the periphery of the glass substrate, in 10 which the thickness of the driver chip is preferably fabricated less than 0.3 mm.

Despite Sato may have disclosed driver chips that are also 0.3 mm or less, the purpose for fabricating driver chips of such thickness is significantly different from that of the present invention. Sato in paragraph [0067] of the cited 15 reference clearly states that the “heat sink 53 becomes protuberant above the driver IC chip 9, and to avoid this, the driver IC chip 9 is thinly polished or buffed”. Therefore, the IC chip 9 disclosed in Sato’s invention is specifically thinned to provide a plane surface.

20 In contrast to Sato, the driver chip of the present invention is thinned to reduce the stress created between the chip and the glass substrate. Moreover, the process to thin the driver chip cannot be accomplished by typical IC fabrication processes. Instead, a series of polishing processes is conducted to achieve a desired thickness and such technique is not commonly found in the conventional 25 art.

Most of all, applicants submit that Sato does not teach, suggest, or in any way provide proper motivation to fabricate a semiconductor module that those skilled in the art would find it reasonable to combine with the liquid crystal 30 module disclosed by the admitted prior art of the present invention, in which the liquid crystal module is specifically fabricated for relieving stress between IC chip

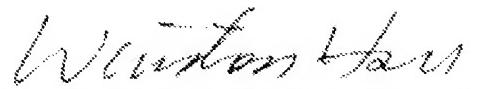
and glass substrate thereby reducing curtain mura between these two units.

As these features are clearly absent in Sato's invention, applicants submit that the liquid crystal display module of the present invention is patentable over
5 the combined teaching of Sato and the admitted prior art of the present invention. Reconsideration of claims 1 and 13 is respectfully requested. As claims 5 and 16-21 are dependent upon claims 1 and 13, applicant asserts that if claims 1 and 13 are found allowable, claims 5 and 16-21 should additionally be found allowable.

10

Applicant respectfully requests that a timely Notice of Allowance be issued in this case.

15 Sincerely yours,



Date: 07/03/2008

Winston Hsu, Patent Agent No. 41,526
P.O. BOX 506, Merrifield, VA 22116, U.S.A.
20 Voice Mail: 302-729-1562
Facsimile: 806-498-6673
e-mail : winstonhsu@naipo.com

Note: Please leave a message in my voice mail if you need to talk to me. (The
25 time in D.C. is 12 hours behind the Taiwan time, i.e. 9 AM in D.C. = 9 PM in Taiwan.)